

Title (en)  
COATING DEVICE FOR POWDER MATERIAL

Title (de)  
PULVERBESCHICHTUNGSVORRICHTUNG

Title (fr)  
DISPOSITIF DE REVETEMENT POUR MATIERE PULVERULENTE

Publication  
**EP 1279487 A4 20050713 (EN)**

Application  
**EP 01919900 A 20010412**

Priority  
• JP 0103142 W 20010412  
• JP 2000111350 A 20000412

Abstract (en)  
[origin: EP1279487A1] A powder material application apparatus capable of applying powder material uniformly onto lower surfaces of plural upper punches, upper surfaces of plural lower punches and inner circumferences of plural dies of a tableting machine. Powder material is applied on a material contacting surface of the lower punch by spraying powder material mixed with air from a powder material spray port for lower punch of a powder material application part for lower punch. Powder material is applied on a material contacting surface of the upper punch wherein powder material is not applied enough according to gravity by spraying powder material mixed with air from a powder material spray port for upper punch while the upper punch moves from an initial end to a terminal end of the powder material spray port for upper punch. The powder material spray port for upper punch is provided along the rotary orbit of the upper punches and is elongated more than the powder material spray port for lower punch.  
<IMAGE>

IPC 1-7  
**B30B 11/08**; A61J 3/06; B30B 15/00; B05B 1/04

IPC 8 full level  
**B05B 1/04** (2006.01); **B30B 11/08** (2006.01); **B30B 15/00** (2006.01)

CPC (source: EP US)  
**B30B 11/08** (2013.01 - EP US); **B30B 15/0011** (2013.01 - EP US); **Y10T 83/9423** (2015.04 - EP US)

Citation (search report)  
• [E] EP 1222917 A1 20020717 - KYOWA HAKKO KOGYO KK [JP]  
• [E] EP 1260220 A1 20021127 - KYOWA HAKKO KOGYO KK [JP] & WO 0126632 A1 20010419 - KYOWA HAKKO KOGYO KK [JP], et al & WO 0152820 A1 20010726 - KYOWA HAKKO KOGYO KK [JP], et al  
• See references of WO 0176860A1

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DOCDB simple family (publication)  
**EP 1279487 A1 20030129**; **EP 1279487 A4 20050713**; AU 4690401 A 20011023; JP 3993768 B2 20071017; US 2004083872 A1 20040506; US 7131828 B2 20061107; WO 0176860 A1 20011018

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**EP 01919900 A 20010412**; AU 4690401 A 20010412; JP 0103142 W 20010412; JP 2001574356 A 20010412; US 25706803 A 20030210